

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the INVENTION ENTITLED COMPONENT MOUNTING CIRCUIT BOARD WITH RESIN-MOLDED SECTION COVERING CIRCUIT PATTERN AND INNER COMPONENT

the specification of which (CHECK applicable BOX(ES))

X -> [] is attached hereto.
-> [X] was filed on September 1, 2000 as U.S. Application No. 0 /
BOX(ES) -> [] was filed as PCT International Application No. PCT/ / on
-> -> and (if applicable to U.S. or PCT application) was amended on

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose all information known to me to be material to patentability as defined in 37 C.F.R. 1.56. I hereby claim foreign priority benefits under 35 U.S.C. 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate filed by me or my assignee disclosing the subject matter claimed in this application and having a filing date (1) before that of the application on which priority is claimed, or (2) if no priority claimed, before the filing date of this application:

PRIOR FOREIGN APPLICATION(S)			Date first Laid-	Date Patented	Priority Claimed
Number	Country	Day/MONTH/Year Filed	open or Published	or Granted	Yes No
11-248664	Japan	2/September/1999			X

I hereby claim domestic priority benefit under 35 U.S.C. 120/365 of the indicated United States applications listed below and PCT international applications listed above or below and, if this is a continuation-in-part (CIP) application, insofar as the subject matter disclosed and claimed in this application is in addition to that disclosed in such prior applications, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in 37 C.F.R. 1.56 which became available between the filing date of each such prior application and the national or PCT international filing date of this application:

PRIOR U.S. PROVISIONAL, NONPROVISIONAL AND/OR PCT APPLICATION(S)			Status	Priority Claimed
Application No. (series code/serial no.)	Day/MONTH/Year Filed		pending, abandoned, patented	Yes No

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

And I hereby appoint Cushman Darby & Cushman, L.L.P., 1100 New York Avenue, N.W., Ninth Floor, East Tower, Washington, D.C. 20005-3918, telephone number (202) 861-3000 (to whom all communications are to be directed), and the below-named persons (of the same address) individually and collectively my attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith and with the resulting patent, and I hereby authorize them to delete names/numbers below of persons no longer with their firm and to act and rely on instructions from and communicate directly with the person/assignee/attorney/firm/organization who/which first sends/sent this case to them and by whom/which I hereby declare that I have consented after full disclosure to be represented unless/until I instruct Cushman Darby & Cushman in writing to the contrary.

Paul N. Kokulis	16773	David W. Brinkman	20817	Chris Comuntzis	31097	David A. Jakopin	32995
Raymond F. Lippitt	17519	George M. Sirilla	18221	Lawrence Harbin	27644	Mark G. Paulson	30793
G. Lloyd Knight	17698	Donald J. Bird	25323	Paul E. White, Jr.	32011	James D. Berquist	34776
Carl G. Love	18781	W. Warren Taltavull	25647	Michelle N. Lester	32331	Timothy J. Klima	34852
Edgar H. Martin	20534	Peter W. Gowdey	25872	Jeffrey A. Simenauer	31993	John P. Moran	30906
William K. West, Jr.	22057	Dale S. Lazar	28872	Robert A. Molan	29834		
Kevin E. Joyce	20508	Glenn J. Perry	28458	G. Paul Edgell	24238		
Edward M. Prince	22429	Kendrew H. Colton	30368	Lynn E. Eccleston	35861		

1. INVENTOR'S SIGNATURE: Tatsuya Nakagawa Date 13 October 2000
Inventor's Name (typed) Tatsuya NAKAGAWA Japan
First Middle Initial Family Name Country of Citizenship
Residence (City) Seto (State/Foreign Country) Japan
Post Office Address (Include Zip Code) c/o Nagoya Branch, TOSHIBA AVE CO, LTD. 991 Anada-cho
Seto, Aichi, Japan

2. INVENTOR'S SIGNATURE: _____ Date _____
Inventor's Name (typed) _____
First Middle Initial Family Name Country of Citizenship
Residence (City) _____ (State/Foreign Country) _____
Post Office Address (Include Zip Code) _____

3. INVENTOR'S SIGNATURE: _____ Date _____
Inventor's Name (typed) _____
First Middle Initial Family Name Country of Citizenship
Residence (City) _____ (State/Foreign Country) _____
Post Office Address (Include Zip Code) _____
(FOR ADDITIONAL INVENTORS, check box [] and attach sheet (CDC-116.2) for same information for each re signature, name, date, citizenship, residence and address.)